v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ч Unit
Peak Repetitive Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Current	$I_{(AV)}$	35	A
Peak forward surge current	I_{FSM}	400	A
I2t Rating for Fusing (t<8.3ms)	I2t	510	A2s
Typical Junction Capacitance(Note1)	CJ	85	pF
Typical Thermal Resistance (Note2)	R_{Jc}	0.6	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

NOTE:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 300mm*300mm*1.6mm cu plate heatsink.

v ̈Ω Parameter	ϒ N Symbol	⊥ ; ↑ Ţ Test Conditions	ω ņ Ö Min	Ɛ ʒ Ö Typ	ω ² Ö Max	D Ч Unit
Reverse Voltage	V_R	I R				

/ Electrical Characteristic Curve

FIG.1-FORWARD CURRENT DERATING CURVE

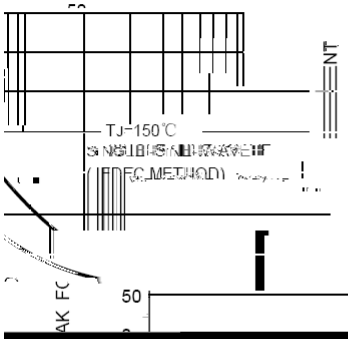
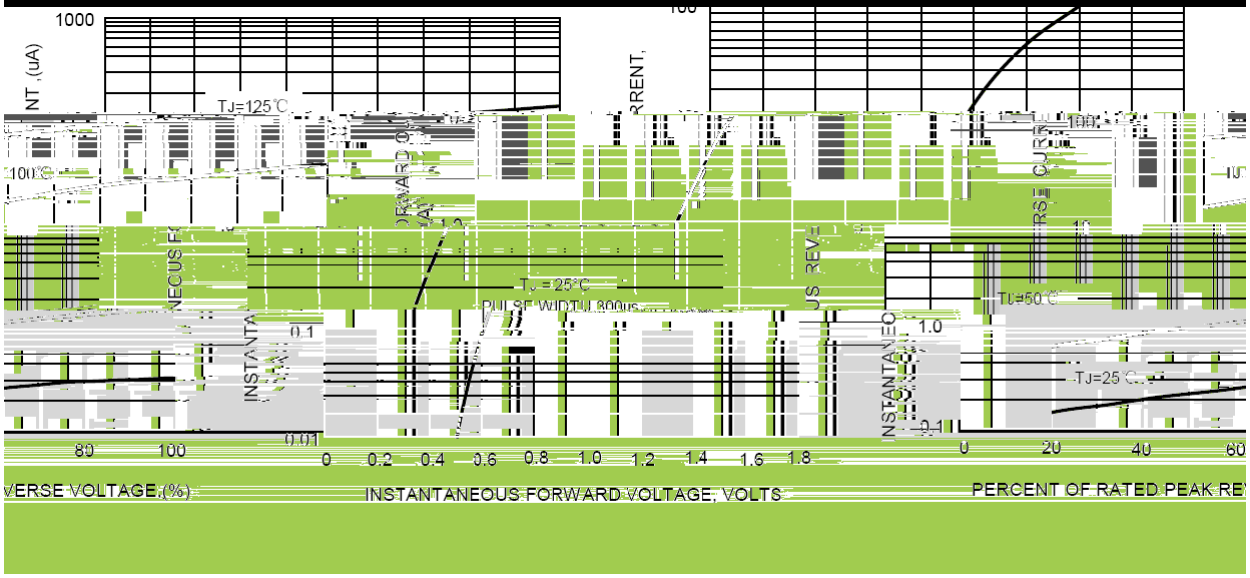
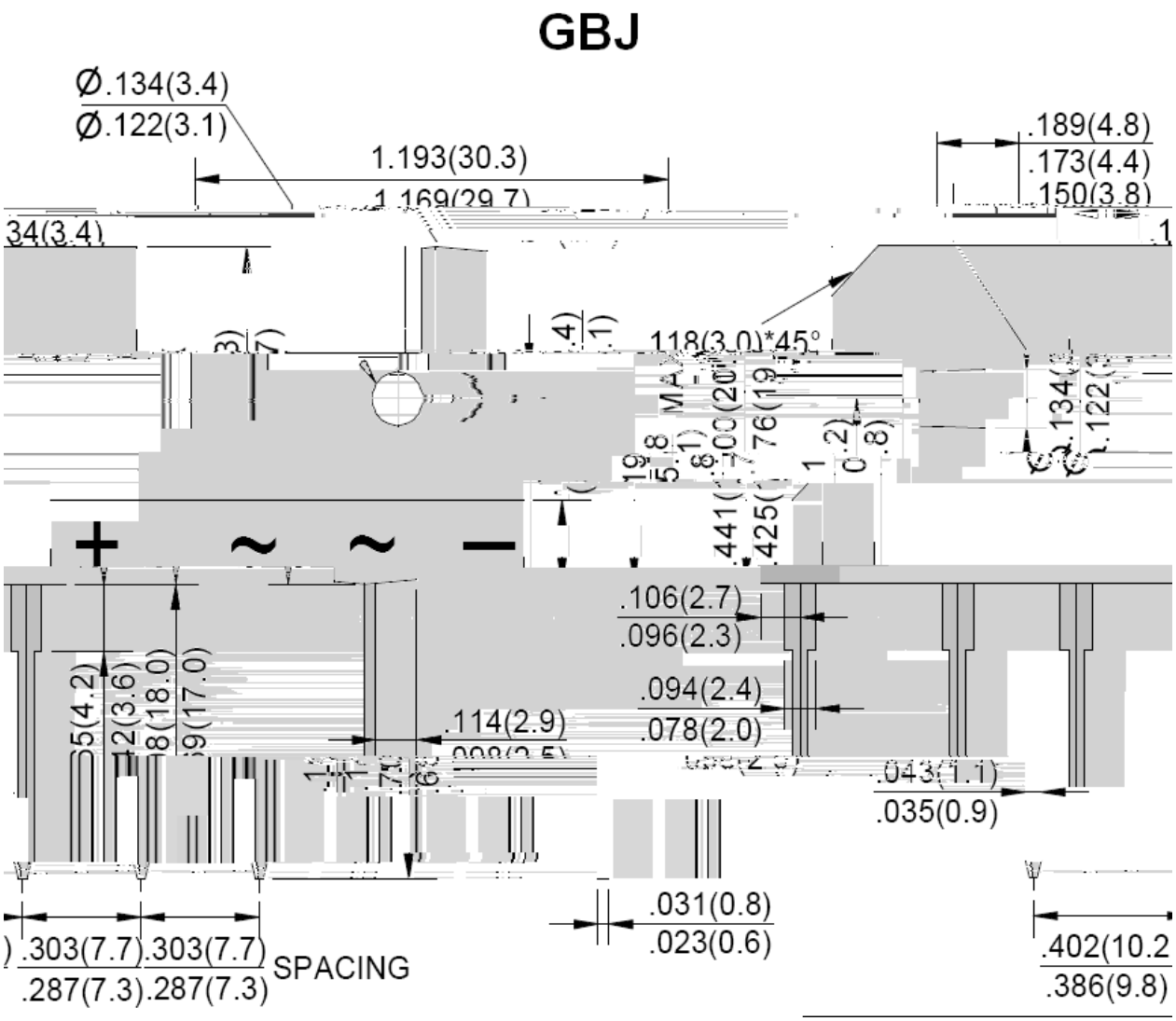


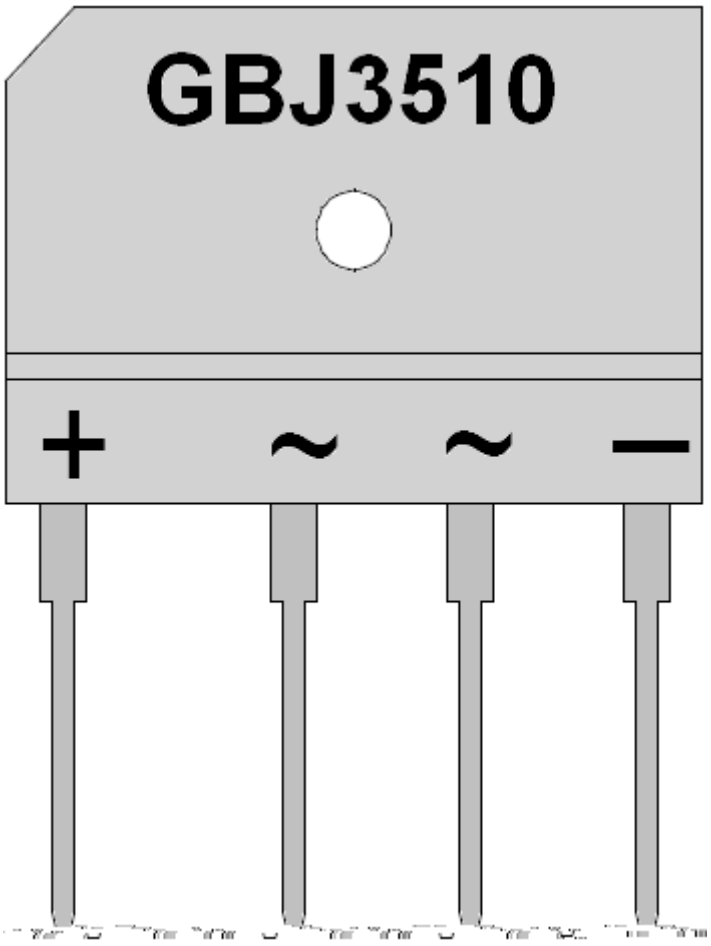
FIG.2-MAXMUN NON-REPETITIVE SURGE CURRENT



/ Package Dimensions



/ Marking Instructions

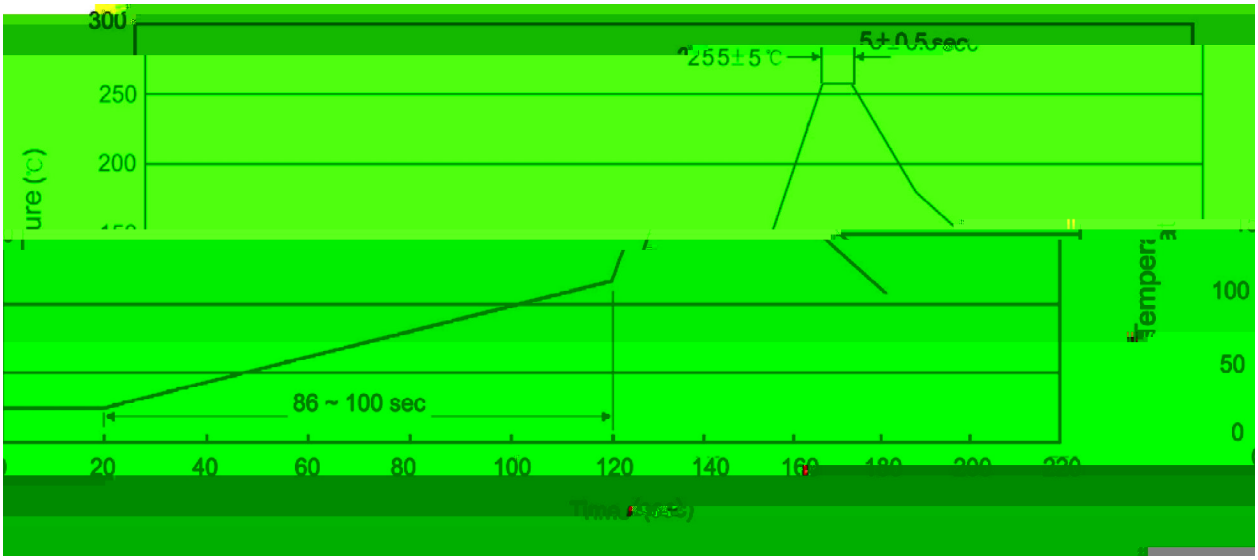


ب ˝ χ

GBJ3510 χ ғ β ʒ N

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( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı `H ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 255 ° 5 ł ı `H ڑ `Y ㅅ ㎛ 5 ° 0.5sec;

3 ì ˙ ㅓ ˛ ɔ ෯ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

`Ọ ţ ㅓ Ł / BULK

Package Type	Units					Dimension (unit mm³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
GBJ	-	-	250	8	2000	-	315×135×48	330×285×215

˛ ㄱ ㅓ Ł / TUBE

Package Type	Units					Dimension (unit mm³)		
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
GBJ	15	40	600	2	1200	471×42×10	500×190×105	525×210×245

/ Notices